

Description

The VST08N058 uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

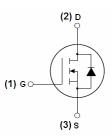
General Features

- V_{DS} =85V, I_{D} =88A $R_{DS(ON)}$ <6.4m Ω @ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification





Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST08N058-TC	VST08N058	TO-220C	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	85	V	
Gate-Source Voltage	V _G s	±20	V	
Drain Current-Continuous	I _D	88	А	
Drain Current-Continuous(T _C =100°ℂ)	I _D (100℃)	65	Α	
Pulsed Drain Current	I _{DM}	320	Α	
Maximum Power Dissipation	P _D	125	W	
Derating factor		0.83	W/℃	
Single pulse avalanche energy (Note 5)	E _{AS}	361	mJ	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	°C	



Shenzhen VSEEI Semiconductor Co., Ltd

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	R ₀ JC	1.2	°C/W	
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	85		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =85V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.5	3.5	4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =44A	-	5.8	6.4	mΩ
Forward Transconductance	g FS	V _{DS} =10V,I _D =44A	-	60	-	S
Dynamic Characteristics (Note4)	,		•	,		
Input Capacitance	C _{lss}	.,	-	3000	-	PF
Output Capacitance	C _{oss}	V_{DS} =40V, V_{GS} =0V, F=1.0MHz	-	442	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIHZ	-	27	-	PF
Switching Characteristics (Note 4)			•	•		
Turn-on Delay Time	t _{d(on)}	V_{DD} =40V, I_{D} =44A V_{GS} =10V, R_{G} =4.7 Ω	-	13.5	-	nS
Turn-on Rise Time	t _r		-	11	-	nS
Turn-Off Delay Time	t _{d(off)}		-	32	-	nS
Turn-Off Fall Time	t _f		-	11	-	nS
Total Gate Charge	Qg	\/ -40\/ -444	-	42.2		nC
Gate-Source Charge	Q _{gs}	$V_{DS}=40V, I_{D}=44A,$ $V_{GS}=10V$	-	21.6		nC
Gate-Drain Charge	Q_{gd}	V _{GS} -10V	-	6.7		nC
Drain-Source Diode Characteristics	·		•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =88A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	88	Α
Reverse Recovery Time	t _{rr}	$T_J = 25$ °C, $I_F = I_S$	-	52		nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	90		nC

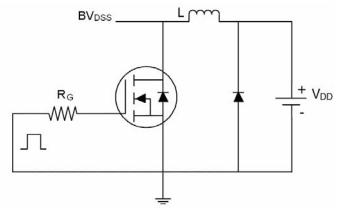
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t \leq 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V_DD=42.5V,V_G=10V,L=0.5mH,Rg=25 Ω

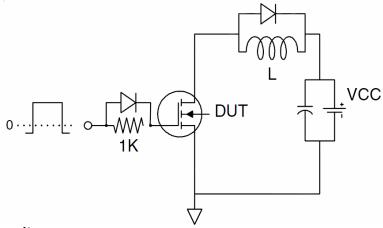


Test Circuit

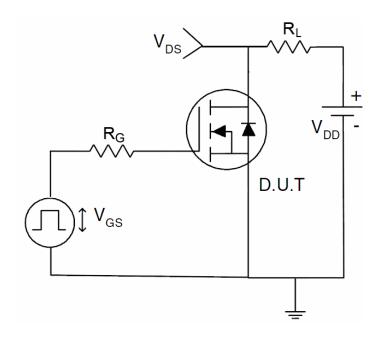
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit







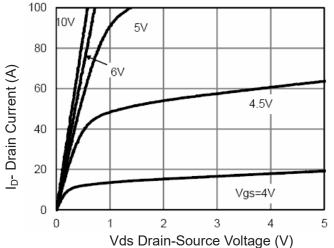


Figure 1 Output Characteristics

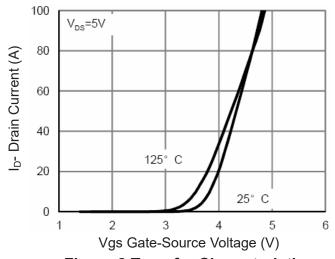


Figure 2 Transfer Characteristics

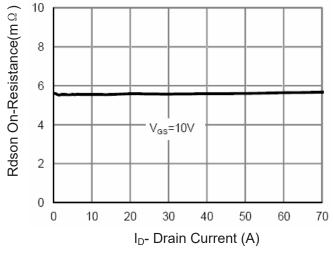


Figure 3 Rdson- Drain Current

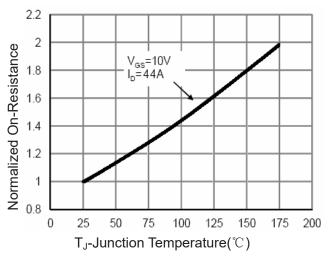


Figure 4 Rdson-JunctionTemperature

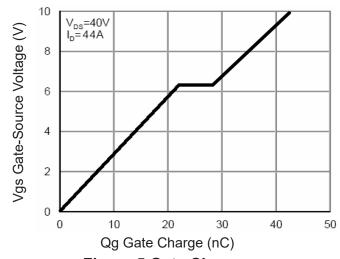


Figure 5 Gate Charge

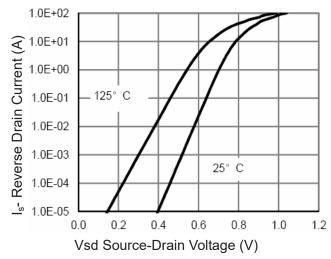


Figure 6 Source- Drain Diode Forward



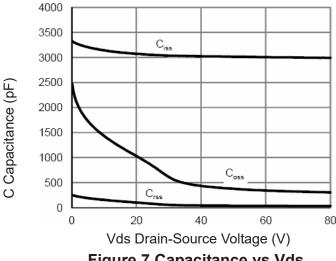
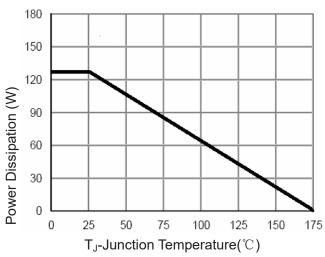


Figure 7 Capacitance vs Vds 1000.0 100.0 R_{DS(ON)} limited Ip- Drain Current (A) 00μs 10.0 1ms 10ms 1.0 T_{J(Max)}=175° C 0.1 T_c=25° C 0.0 100 0.01 1000

Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



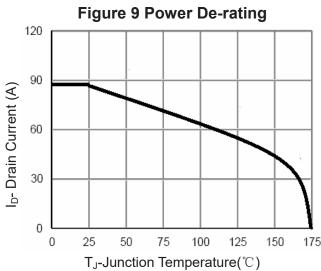
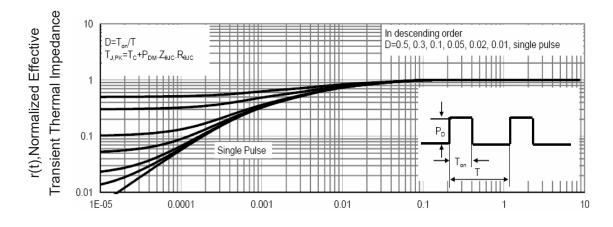


Figure 10 Current De-rating



Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance